# Migration from EA3 package to EA3.1 package

## SDK Setup:

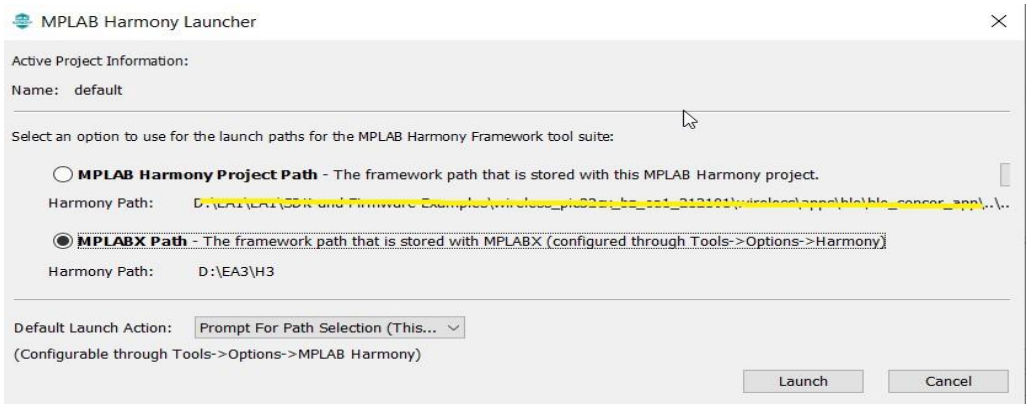
Below changes on the SDK setup to be followed while migrating from EA3 to EA3.1 package. The steps are detailed in **\Documentation\PIC32CX-BZWBZ45x SDK Setup.pdf**

## Key Changes:

1. **Starting from EA3.1 release all application examples released will have the device name of "WBZ451", WBZ451 is RF module based of Soc PIC32CX1012BZ25048. All GPIO's and Analog/Digital peripherals available in the Soc are available in the RF module.**
2. **Sleep Mode –** Special Clock control settings are required for both BLE and Zigbee users to control sleep mode. This is accomplished by copying "plib_clk.c.ftl" file. Steps documented in SDK setup document
3. **MPLAB X IDE Version: I**t is recommended to use the v5.50 version of MPLAB X IDE as mentioned in **\MPLAB X IDE** folder.
4. **Compiler Version:** Update the XC32 compiler to newer version, XC32 v3.01 version as mentioned in **\Compiler**.
5. **DFP pack:** Update the DFP pack to Microchip.PIC32CX-BZ_DFP-1.0.80 available in **\MPLAB X IDE** folder.
6. **H3 Framework Setup:** (CSP, Core, BSP etc..) are added to development environment using manifest files. See SDK setup document for more details on this. Demo projects available as part of this Early Adopter release are dependent on the H3 configuration mentioned in the manifest files. Users should follow all the steps mentioned in the SDK setup document

## Example Projects:

1. There are low power demo examples (BLE, Zigbee) added in EA3.1 package and can be seen inside **H3\wireless_apps_pic32cxbz2_wbz45\apps** with protocol specific folders. The EA3.1 BLE demo examples are available in **\H3\wireless_apps_pic32cxbz2_wbz45\apps\ble**
2. As there are changes done in the H3 configuration structure for BLE stack, and DFP pack is also to be updated, the recommended and easy way of porting the customer project developed on EA3 package to EA3.1 package would be to
    a. Take the equivalent example project from EA3 package
    b. Migrate the customer code changes done in EA3 to the respective EA3.1 project
    **Note: EA3.1 Projects have "WBZ451" set as the device name for these projects. WBZ451 RF module is based on "PIC32CX1012BZ25048" Soc. All GPIO/Digital and Analog peripherals available on Soc are also available on the RF module.**
    c. H3 configurator can be used to add peripheral driver components (if required) Make sure to provide the H3 framework path of EA3.1 package **(\H3**) while opening the H3 configurator, and DFP pointing to PIC32CX-BZ_DFP-1.0.80 version





3. There are new feature additions and few API changes done in EA3.1. Refer to **\H3\wireless\docs\release_notes** for details.